

[Name of Document] Abstract

A method of inspecting a substrate to be repeatedly treated along a predetermined transfer way in a plurality of kinds of different treatment apparatuses, includes: imaging a substrate that has been treated in one of the treatment apparatuses, to acquire a first substrate image; imaging a substrate that has been an object for imaging the first substrate image and further treated in another treatment apparatus different from the one treatment apparatus after treated in the one treatment apparatus, to acquire a second substrate image; then performing defect inspection, based on the first substrate image and the second substrate image; and identifying, depending on whether or not a defect detected from the second substrate image is not detected from the first substrate image, whether or not the defect is caused by a treatment after the first substrate image is acquired and a treatment before the second substrate image is acquired.